

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	((("4986247") or ("4554130") or ("6048432")).PN.	USPAT	OR	OFF	2005/10/30 15:46
S1	520	228/193.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:04
S2	294	228/194.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:04
S3	89	228/195.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:18
S4	337	228/245.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:05
S5	437	228/246.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:05
S6	463	228/248.1.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:05
S7	494	228/234.1.ccls.	US-PGP UB; USPAT	OR	ON	2005/10/21 14:05
S8	2213	S1 or S2 or S3 or S4 or S5 or S6 or7	US-PGP UB; USPAT	OR	ON	2005/10/21 14:18
S9	4881	S1 or S2 or S3 or S4 or S5 or S6 or7	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 14:19

S10	0	S9 and (optic\$3 or substrate or (laser near5 diode) or electronic or circuit or chip)with Bond\$3 and ( diffus\$3 or weld\$3or braz\$3 or solder\$9) and coat\$3 and ( electroplat\$3 or electrodeposit\$3 or plat\$3 or electroless or electrophoric)and (9metal or dielectri) with particle0	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 14:41
S11	88	S9 and (optic\$3 or substrate or (laser near5 diode) or electronic or circuit or chip)and Bond\$3 and ( diffus\$3 or weld\$3 or braz\$3 or solder\$9) and coat\$3 and ( electroplat\$3 or electrodeposit\$3 or plat\$3 or electroless or electrophoric)and (metal or dielectric) same particle	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 15:42
S12	68	S9 and (optic\$3 or substrate or (laser near5 diode) or electronic or circuit or chip)and Bond\$3 and ( diffus\$3 or weld\$3 or braz\$3 or solder\$9) and coat\$3 and ( electroplat\$3 or electrodeposit\$3 or plat\$3 or electroless or electrophoric)and (metal or dielectric) same particle and (below or lower or less) and ( melt\$3 or liquid\$9) near20 ( point or temperature)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 15:04
S13	14	("20030035975"   "3954486"   "3979187"   "4608321"   "4624404"   "4645115"   "4860942"   "4932582"   "4942999"   "4952454"   "5525432"   "5807626"   "6057513"   "6390354").PN. OR ("6857556").URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/21 15:40

S14	15	(("3602979") or ("3923231") or ("4325734") or ("4614296") or ("5009360") or ("5025304") or ("5392982") or ("5542602") or ("5621607") or ("5812925") or ("6087021") or ("6187450") or ("6199751") or ("6340113") or ("6520401")).PN.	US-PGP UB; USPAT	OR	OFF	2005/10/21 16:06
S15	2	S14 and (optic\$3 or substrate or (laser near5 diode) or electronic or circuit or chip)and Bond\$3 and ( diffus\$3 or weld\$3 or braz\$3 or solder\$9) and coat\$3 and ( electroplat\$3 or electrodeposit\$3 or plat\$3 or electroless or electrophoric)and (metal or dielectric) same particle	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 15:43
S16	46	("3574579"   "3650714"   "3915369"   "3949263"   "4009027"   "4239502"   "4396677"   "4750914"   "4776862"   "4899922"   "4968326"   "5143523"). PN. OR ("5392982"). URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/21 15:44
S17	23	("3716347"   "4029476"   "4126451"   "4324356"   "4331286"   "4412643"   "4434211"   "4485961"   "4676843"   "4710235"   "4804132"   "5083697"   "5288351"   "5318214"   "5361971"   "5564064"). PN. OR ("5812925"). URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/21 16:10
S18	7	("2438967"   "3579808"). PN. OR ("3923231"). URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/21 17:07

S19	68	219/129.ccls.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/21 17:11
S20	39399	(join\$3 or bond\$3 or composite )same (copper or Cu) same (Indium or In)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:17
S21	8091	(join\$3 or bond\$3 or composite )near20 (copper or Cu) near20 (Indium or In)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:17
S22	0	S21 and diffus\$3 near50 parrticle	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:14
S23	2199	S21 and diffus\$3	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:18
S24	116	S23 and optic\$3 near50( circuit or semiconductor)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:19

S25	2457	(join\$3 or bond\$3 or composite )same (copper or Cu) same Indium	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:17
S26	710	(join\$3 or bond\$3 or composite )near20 (copper or Cu) near20 Indium	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:17
S27	764	S25 and diffus\$3	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:18
S28	100	S27 and optic\$3 near50( circuit or semiconductor)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/21 17:24
S29	2	((("6348273") or ("6440578")).PN.	US-PGP UB; USPAT	OR	OFF	2005/10/21 17:24
S30	2	((("4332341") or ("6121576")).PN.	US-PGP UB; USPAT	OR	OFF	2005/10/24 07:06
S31	69	("3292240"   "3373481"   "3504096"   "3555664"   "3561107"   "3591839"   "4143385").PN. OR ("4332341").URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/24 07:07

S32	44	("4332341"   "4371912"   "4638348"   "4761681"   "4841355"   "4868712"   "4956694"   "5010233"   "5012323"   "5128831"   "5172049"   "5231304"   "5239447"   "5311401"   "5313096"   "5373189"   "5384689"   "5397997"   "5616958"   "5625221"   "5637536"   "5639695"   "5639696"   "5642261"   "5648679"   "5668405"   "5677566"   "5686318"   "5834945"   "5911897"). PN. OR ("6121576"). URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/24 07:35
S33	69	("3292240"   "3373481"   "3504096"   "3555664"   "3561107"   "3591839"   "4143385").PN. OR ("4332341").URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/24 08:14
S34	9	low near50 (temperature or melt\$3) near50 bond\$3 near50( particle or dielectric) and diffus\$3 and sublim\$3	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/24 08:18
S35	1121	low near50 (temperature or melt\$3) near50 bond\$3 near50( particle or dielectric)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/24 08:18
S36	862	S35 and ( electroless of electrophoretic or electroplat\$3 or plat\$3 or deposit\$3 or electrodeposit\$3 or coat\$3)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/24 08:22

S37	3	S36 and (diffus\$3 near5 barrier)and (mecury or amalgam\$4) and (naphtalene or (carbon near5 dioxide))	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/24 08:26
S38	4	S36 and (diffus\$3 near5 barrier) and (naphtalene or (carbon near5 dioxide))	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/24 08:26
S39	31	("5098861"   "5102821"   "5168078"   "5183769"   "5266135"   "5362667"   "5387555").PN. OR ("5849627").URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/24 08:27
S40	2	("6863209" or "6117299" ).pn.	US-PGP UB; USPAT	OR	ON	2005/10/29 11:34
S41	1332	228/193-195.ccls.	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 11:35
S42	1932	228/245,246,248.1,248.5, 234.1.ccls.	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 11:35
S43	3182	S41 or S42	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 11:36

S44	417	S43 and ( optic\$3 or substrate or electronic)and ( solder\$3 or bond\$9 or join\$9 or weld\$3 or braz\$3) and (electroless or electroplat\$3 or plat\$3 or electrodeposit\$3 or depoSit\$3 or coat\$) and (below or less or low\$5) with (melt\$9 or liquid\$9)with (point or temperature)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 13:58
S45	0	S44 and (particles or foam) and ( apply\$3 or applied) with (electric\$3 near5 current) with vibrat\$4 with (corrod\$3 or corrosion) with (pressure or press\$3)with (displac\$6 near5 react\$3)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 12:16
S46	3	S44 and (particles or foam) and ( apply\$3 or applied) and (electric\$3 near5 current) and vibrat\$4 and (corrod\$3 or corrosion) and (pressure or press\$3)and (displac\$6 near5 react\$3)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 12:18
S47	6	( optic\$3 or substrate or electronic)and ( solder\$3 or bond\$9 or join\$9 or weld\$3 or braz\$3) and (electroless or electroplat\$3 or plat\$3 or electrodeposit\$3 or depoSit\$3 or coat\$) and (below or less or low\$5) with (melt\$9 or liquid\$9)with (point or temperature)and (particles or foam) and ( apply\$3 or applied) and (electric\$3 near5 current) and vibrat\$4 and (corrod\$3 or corrosion) and (pressure or press\$3)and (displac\$6 near5 react\$3)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 12:22



S48	6	( optic\$3 or substrate or electronic)and ( solder\$3 or bond\$9 or join\$9 or weld\$3 or braz\$3) and (electroless or electroplat\$3 or plat\$3 or electrodeposit\$3 or depoSit\$3 or coat\$) and (below or less or low\$5) with (melt\$9 or liquid\$9)with (point or temperature)and (particles) and ( apply\$3 or applied) and (electric\$3 near5 current) and vibrat\$4 and (corrod\$3 or corrosion) and (pressure or press\$3)and (displac\$6 near5 react\$3)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 12:23
S49	323	( optic\$3 or substrate or electronic)and ( solder\$3 or bond\$9 or join\$9 or weld\$3 or braz\$3) and (electroless or electroplat\$3 or plat\$3 or electrodeposit\$3 or depoSit\$3 or coat\$) and (below or less or low\$5) with (melt\$9 or liquid\$9)with (point or temperature)and (particles) and ( apply\$3 or applied) and (electric\$3 near5 current) and vibrat\$4 and (corrod\$3 or corrosion) and (pressure or press\$3)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 12:24
S50	29	("3234031"   "3530568"   "3675311"   "3678570"   "3723078"   "3769101"). PN. OR ("4059217"). URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2005/10/29 12:55

S51	622	(Bond\$3 or join\$3) same (component with optic\$3) and (below or less or low\$5) with (melt\$9 or liquid\$9)with (point or temperature)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 14:18
S52	215	S51 and ((chemical with react\$3) or corrod\$3 or corrosion or vibrat\$3)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 14:00
S53	670	(Bond\$3 or join\$3) with (component with optic\$3)with substrate	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 14:21
S54	0	S53 and (electroplat\$3 or elctroless) with (dielectric or glass or ceramic or rubber)with particle	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 14:22
S55	37	S53 and (electroplat\$3 or elctroless)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 14:25

S56	23	S53 and (dielectric or glass or ceramic or rubber)with particle	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/29 14:26
S57	828	428/548,554,558,.ccls.	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 13:41
S58	2991	419/8,22,36,48,57.ccls.	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 13:42
S59	3715	S57 or S58	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 13:42
S60	0	S59 and (bond\$3 or join\$3) with (below or lower or less) with ( melt\$3 or liqui\$9) with (point or temperature)with pass\$3 with ( current or electric\$3 or vibrat\$3 or (displac\$9 near20 react\$3))	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 13:47

S61	34	(bond\$3 or join\$3) with (below or lower or less) with ( melt\$3 or liqui\$9) with (point or temperature)with pass\$3 with ( current or electric\$3 or vibrat\$3 or (displac\$9 near20 react\$3))	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 13:58
S62	0	(bond\$3 or join\$3) with component with (substrate or electronic or optic\$3) with (interlay\$3 or overlay\$3 or interpos\$3 or between) with (particles or dielectric) with ( sublim\$5 or (carbon adj dioxide) or naphthalene)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 14:03
S63	162	(bond\$3 or join\$3) with component with (substrate or electronic or optic\$3) and (interlay\$3 or overlay\$3 or interpos\$3 or between) and (particles or dielectric)and ( sublim\$5 or (carbon adj dioxide) or naphthalene)	US-PGP UB; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/10/30 14:03